



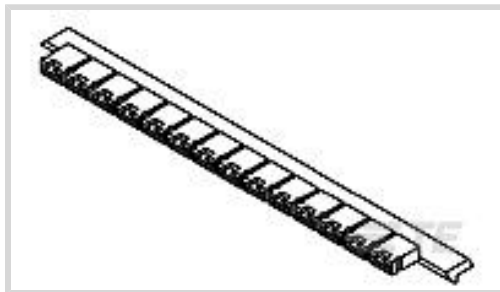
AMP

TE Internal #: 142270-3

Board-to-Board Jumpers & Shunts, AMPMODU MOD IV, Open Top, Board-to-Board, 2 Position, .1 in [2.54 mm] Centerline, Printed Circuit Board, Signal

[View on TE.com >](#)

Connectors > PCB Connectors > Board-to-Board Connectors > Board-to-Board Jumpers & Shunts



Shunt Type: **AMPMODU MOD IV**

Shunt Style: **Open Top**

Connector System: **Board-to-Board**

Number of Positions: **2**

Centerline (Pitch): **2.54 mm [ .1 in ]**

**Features**

**Product Type Features**

Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

**Configuration Features**

Number of Positions	2
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**Body Features**

Handle	Without
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**Contact Features**

Contact Mating Area Plating Material Thickness	3 µm[118.1 µin]
Contact Mating Area Plating Material	Tin
Contact Base Material	Beryllium Copper
Shunt Type	AMPMODU MOD IV
Shunt Style	Open Top
Contact Current Rating (Max)	3 A

**Housing Features**

Housing Material	Glass Filled PBT
Housing Color	Black
Centerline (Pitch)	2.54 mm[.1 in]



### Dimensions

Product Height	6.3 mm[.248 in]
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### Usage Conditions

Operating Temperature Range	-40 – 85 °C[-40 – 185 °F]
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### Operation/Application

Circuit Application	Signal
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### Industry Standards

CSA Certified	Yes
UL Rating	Recognized
UL Flammability Rating	UL 94V-0

### Packaging Features

Jumper & Shunt Packaging	Breakaway Strip of 14 Pieces
Packaging Quantity	1400
Packaging Method	Box

### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Not applicable for solder process capability

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides

on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

## Compatible Parts



## Documents

### Product Drawings

#### CONNECTOR SHUNT 2 P

English

### CAD Files

#### 3D PDF

3D

#### Customer View Model

[ENG\\_CVM\\_CVM\\_142270-3\\_C.2d\\_dxf.zip](#)

English

#### Customer View Model

[ENG\\_CVM\\_CVM\\_142270-3\\_C.3d\\_igs.zip](#)

English

#### Customer View Model

[ENG\\_CVM\\_CVM\\_142270-3\\_C.3d\\_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

### Product Specifications

#### Product Specification

English

**STRAP D'INTERCONNEXION AU PAS DE 2,54 mm**

English